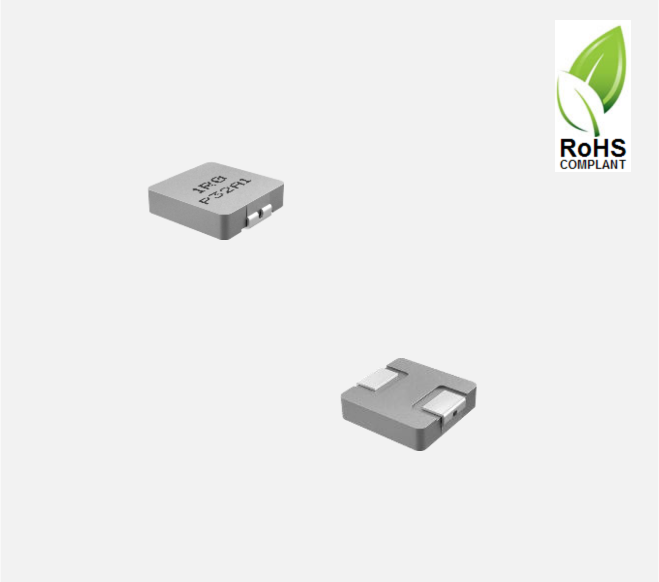
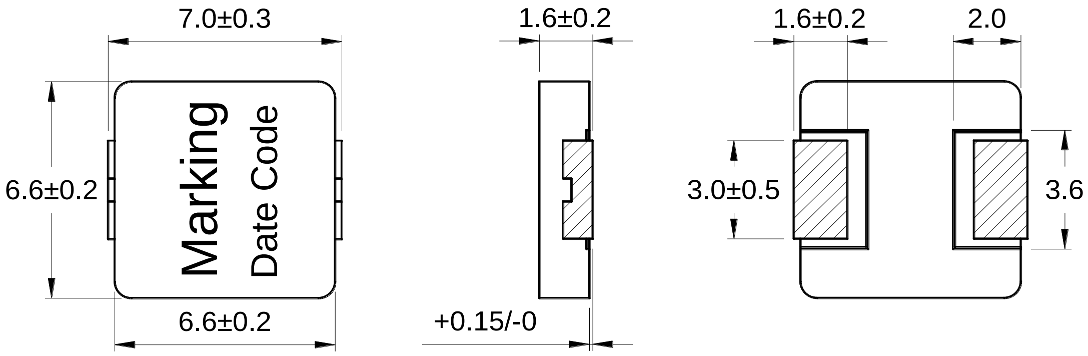
Molding Power Choke
- CSAB0718 Series



Outline:
产品概要

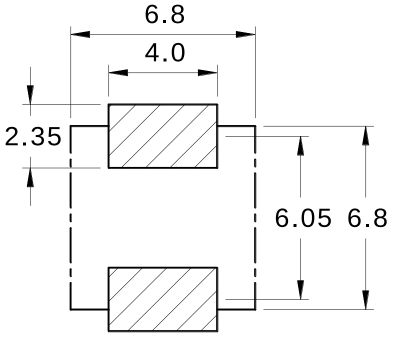
- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI).
  磁屏蔽结构：抗电磁干扰(EMI)性能强。
- A composite structure, ultra low buzz noise.
  一体成型结构，超低蜂鸣噪音。
- Low loss, high efficiency, wide application frequency.
  低损耗，高效率，应用频率宽。
- Lightweight design, save space, suitable for high density SMT.
  轻薄型设计，节省空间，适合高密度贴装。
- Die-casting by low loss alloy powder: low impedance, small parasitic capacitance.
  低损耗合金粉末压铸：低阻抗，寄生电容小。
- Operating temperature : -40℃ ～ +125℃ (Including coil’s temperature rise)
  工作温度：-40℃ ～ +125℃ (包含线圈发热)

1 Appearance and dimensions (mm)
外形尺寸

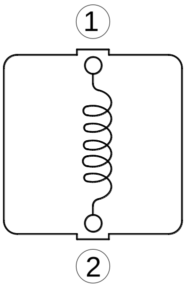


2 Marking
印字标识

3 Reference land pattern (mm)
参考基板尺寸



4 Schematic
原理图



5 Electrical characteristics
电气特性

Part No. 型 号	Inductance (μH) 电感值 ※1	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2	Temperature rise current (A) 温升电流 ※3
	±20%	Typical	Max	Typical	Typical
CSAB0718-R10M	0.10	2.10	2.50	33.0	20.5
CSAB0718-R15M	0.15	4.00	5.00	27.0	15.0
CSAB0718-R47M	0.47	8.90	10.0	18.0	10.0
CSAB0718-R82M	0.82	11.9	14.5	14.0	8.60
CSAB0718-1R0M	1.00	15.4	17.0	12.0	7.60
CSAB0718-1R5M	1.50	25.8	28.0	9.00	5.90
CSAB0718-2R2M	2.20	30.5	35.0	7.50	5.40
CSAB0718-4R7M	4.70	61.5	70.0	5.00	3.70
CSAB0718-6R8M	6.80	101	110	3.50	2.90

■ All data is tested based on 25℃ ambient temperature.
所有数据基于环境温度 25℃条件下测试。

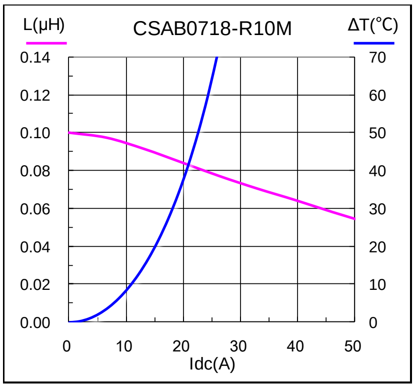
※1 Inductance measure condition at 100kHz, 1V.
电感测试条件为 100kHz, 1V。

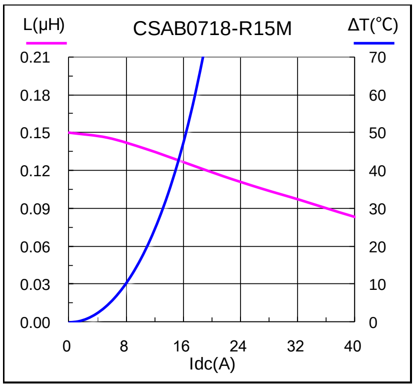
※2 Saturation current：the actual value of DC current when the inductance decrease 30% of its initial value.
饱和电流：电感值下降其初始值的 30%时所加载的实际直流电流值。

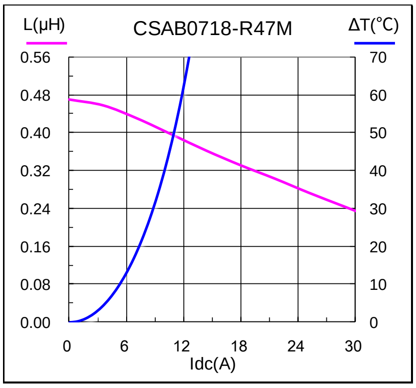
※3 Temperature rise current：the actual value of DC current when the temperature rise is ΔT40℃(Ta=25℃).
温升电流：使产品温度上升到 ΔT40℃时所加载的实际直流电流值(Ta=25℃)。

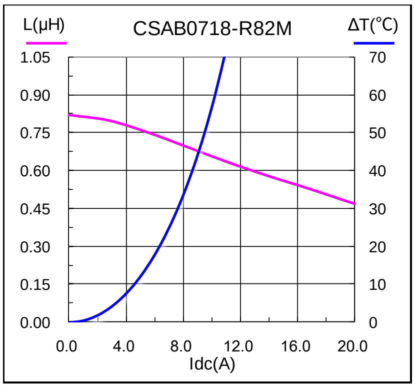
※ Special remind：Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.
特别提醒：线路设计，组件布局，印刷线路板(PWB)尺寸及厚度，散热系统等均会影响产品温度。
请务必在最终应用时，验证产品发热状况。

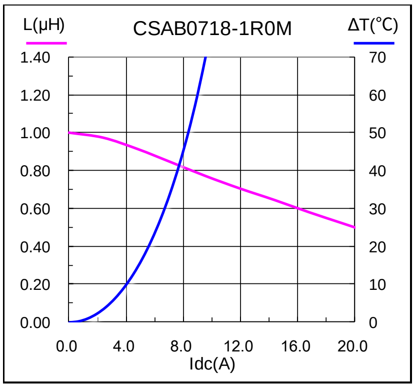
6 Saturation current VS temperature rise current curve
饱和电流 VS 温升电流曲线

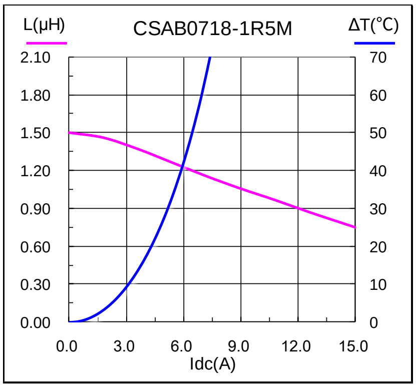


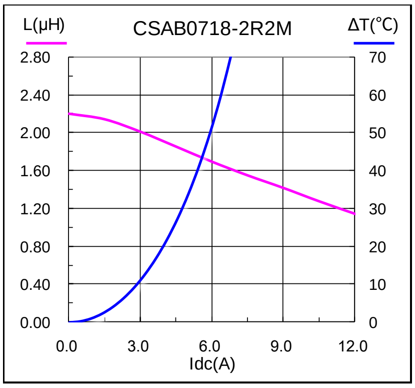


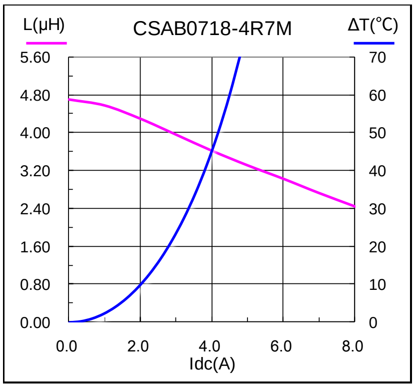


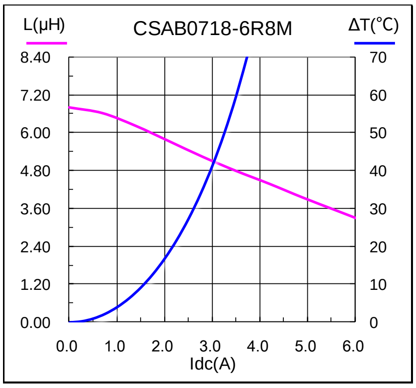






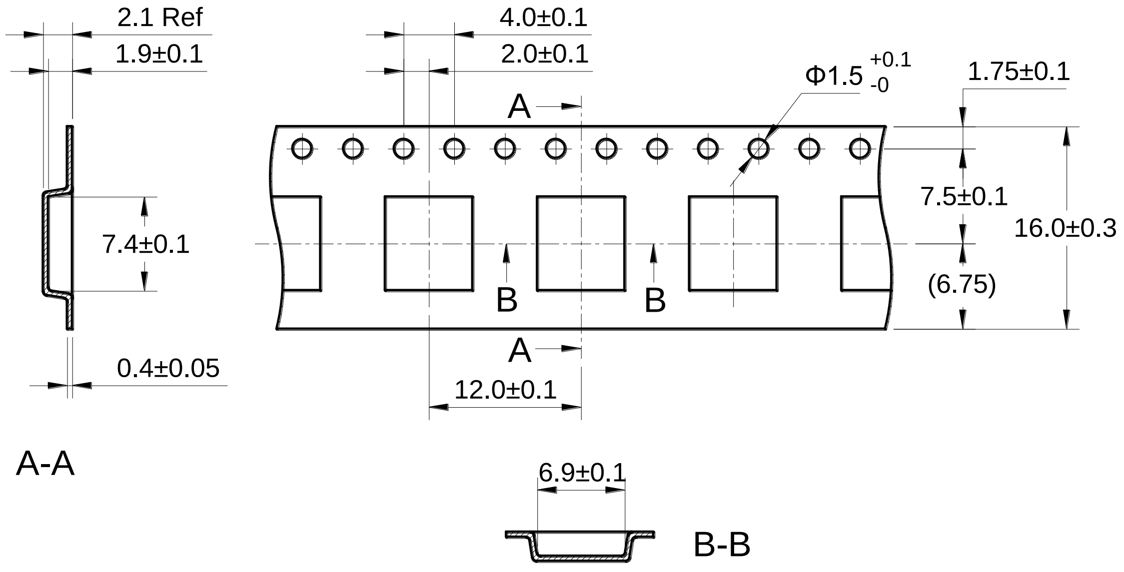






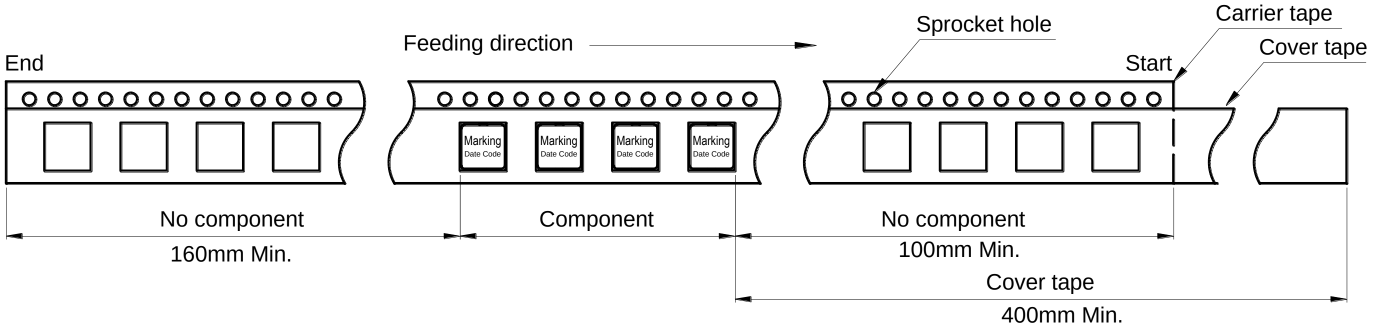
7 Packing specification
包装规格

7.1 Carrier tape dimensions (mm)
载带尺寸



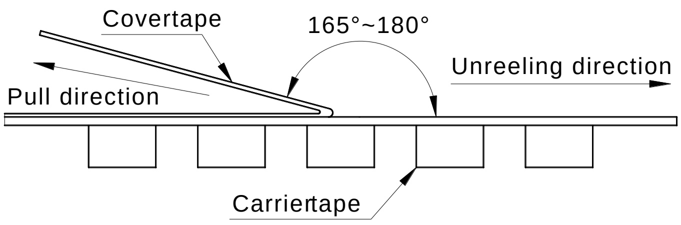
※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape direction
捆包方向

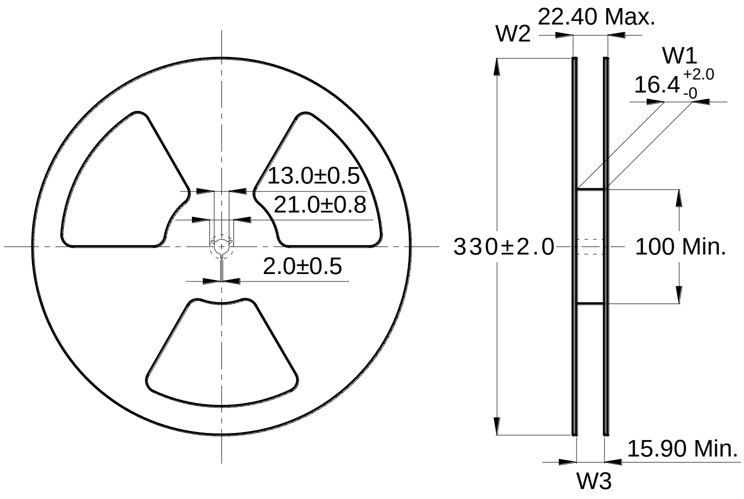


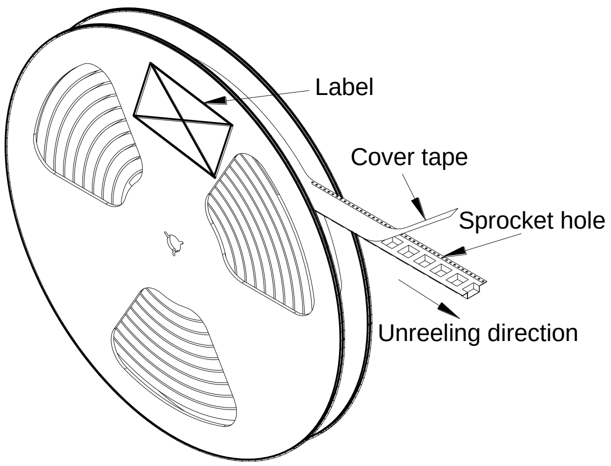
7.3 Cover tape peel off condition
盖带剥离条件

- ■ Cover tape peel force shall be 0.1 to 1.3N.
  盖带剥离力度为 0.1～1.3N。
- ■ Reference peel speed 300±10mm/min.
  参考剥离速度 300±10mm/分钟。



7.4 Reel dimensions (mm)
卷盘尺寸





7.5 Carton dimensions and packing quantity
包装箱尺寸和包装数量

- Inner Carton：340×340×95mm
  内包装盒
- Out Carton ：355×355×385mm
  外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSAB0718	2000pcs	(2000×3) = 6000pcs	(6000×3) = 18000pcs

7.6 Label making
标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label
产品标签

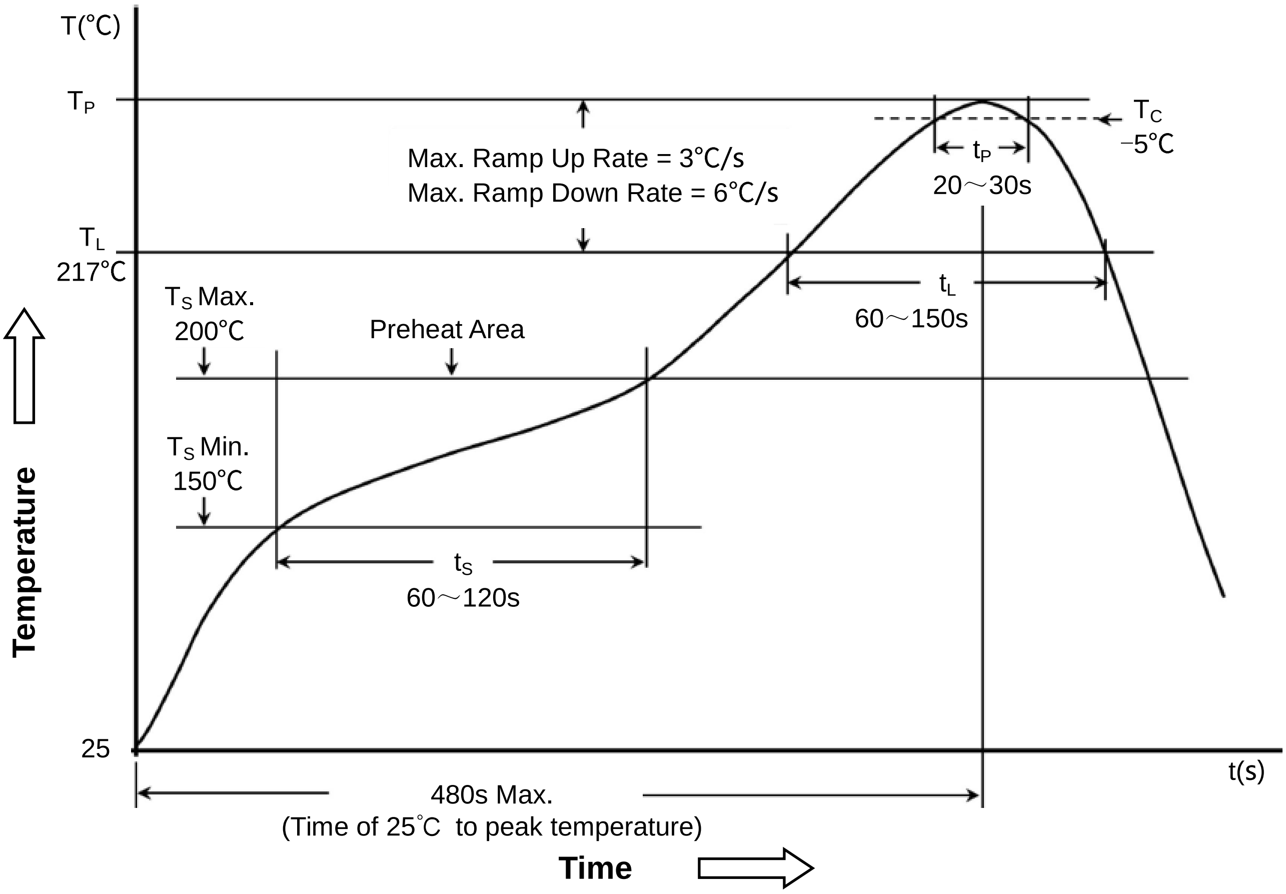
- Part No.
  产品型号
- Electrical Information
  产品电性信息
- Quantity
  数 量
- Packing No.
  包装流水号

Shipping Label
运输标签

- Customer Name
  客户名称
- Customer Part No.
  客户型号
- Supplier Part No.
  供应商型号
- Supplier Name
  供应商名称
- Country of origin
  产品产地

8 Soldering specification
焊接规格

8.1 Reflow profile for SMT components
SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)
封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm^3	350～2000 mm^3	>2000 mm^3
PB-Free Assembly 无铅装配	<1.6mm	260℃	260℃	260℃
	1.6～2.5mm	260℃	250℃	245℃
	≥2.5mm	250℃	245℃	245℃

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。